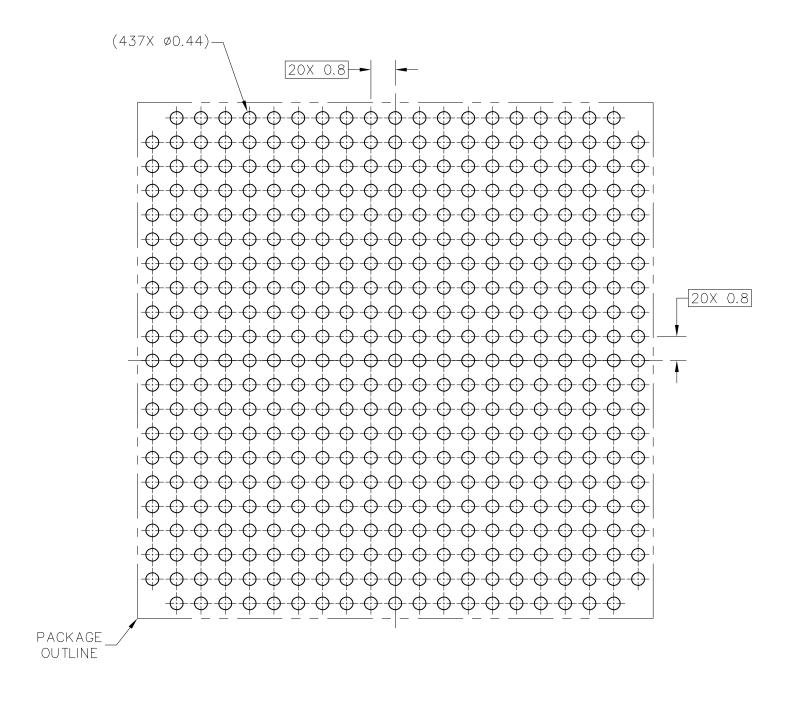


BOTTOM VIEW



© NXP B.V.	ALL RIGHTS RESERVED		DATE: 08	B MAR 2022
MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON-JFDFC	DRAWING NUMBER: 98ASA01918D	REVISION:	PAGE: 1 OF6
TRINT VERSION NOT TO SOALE	NON GEBEG	30/(3/(01310)		1 010

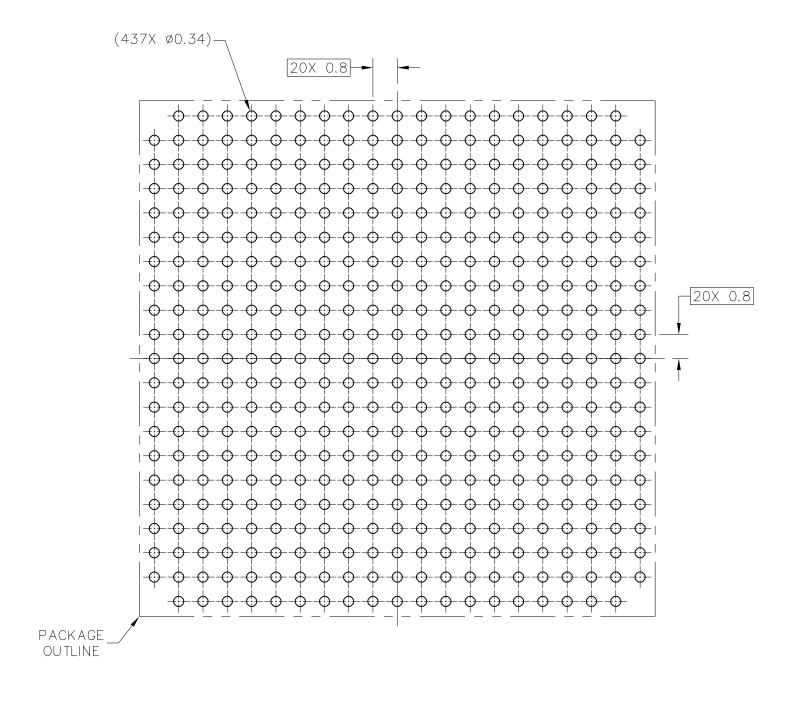


PCB DESIGN GUIDELINES - SOLDER MASK OPENING PATTERN

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.



© NXP B.V.	ALL RIGHTS RESERVED		DATE: 08	3 MAR 2022
MECHANICAL OUTLINE	STANDARD:	DRAWING NUMBER:	REVISION:	PAGE:
PRINT VERSION NOT TO SCALE	NON-JEDEC	98ASA01918D	ΧO	2

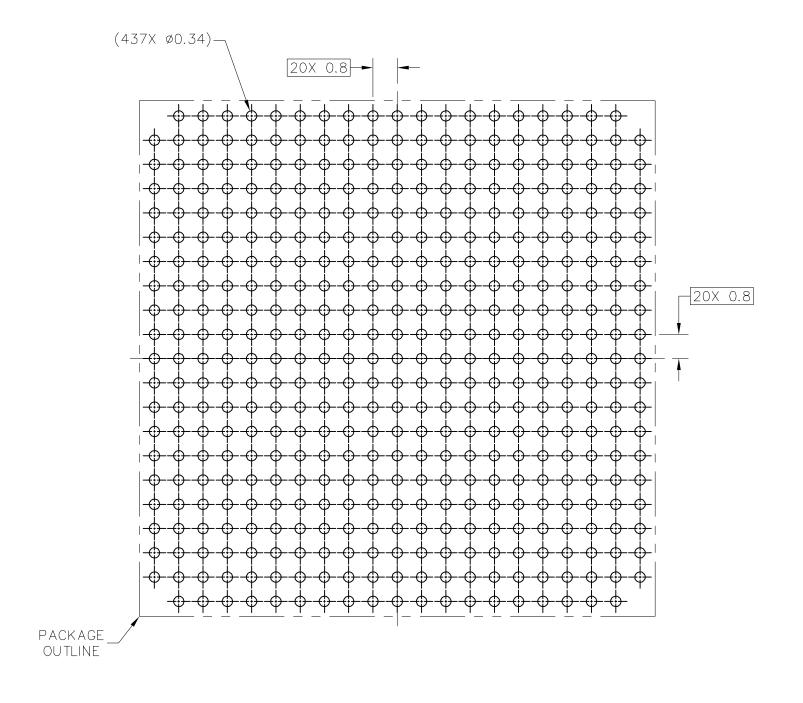


PCB DESIGN GUIDELINES - I/O PADS AND SOLDERABLE AREA

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.



© NXP B.V.	ALL RIGHTS RESERVED		DATE: 08	3 MAR 2022
MECHANICAL OUTLINE	STANDARD:	DRAWING NUMBER:	REVISION:	PAGE:
PRINT VERSION NOT TO SCALE	NON-JEDEC	98ASA01918D	X0	3



RECOMMENDED STENCIL THICKNESS 0.125 MM

PCB DESIGN GUIDELINES - SOLDER PASTE STENCIL

THIS SHEET SERVES ONLY AS A GUIDELINE TO HELP DEVELOP A USER SPECIFIC SOLUTION. DEVELOPMENT EFFORT WILL STILL BE REQUIRED BY END USERS TO OPTIMIZE PCB MOUNTING PROCESSES AND BOARD DESIGN IN ORDER TO MEET INDIVIDUAL/SPECIFIC REQUIREMENTS.



© NXP B.V.	ALL RIGHTS RESERVED		DATE: 08	3 MAR 2022
MECHANICAL OUTLINE	STANDARD:	DRAWING NUMBER:	REVISION:	PAGE:
PRINT VERSION NOT TO SCALE	NON-JEDEC	98ASA01918D	X0	4

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.



PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.



MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.



DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.



PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.



© NXP B.V.	ALL RIGHTS RESERVED		DATE: 08	3 MAR 2022
MECHANICAL OUTLINE	STANDARD:	DRAWING NUMBER:	REVISION:	PAGE:
PRINT VERSION NOT TO SCALE	NON-JEDEC	98ASA01918D	X0	5